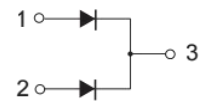


FEATURES

Extra small power mold type

 Low V_F

High reliability

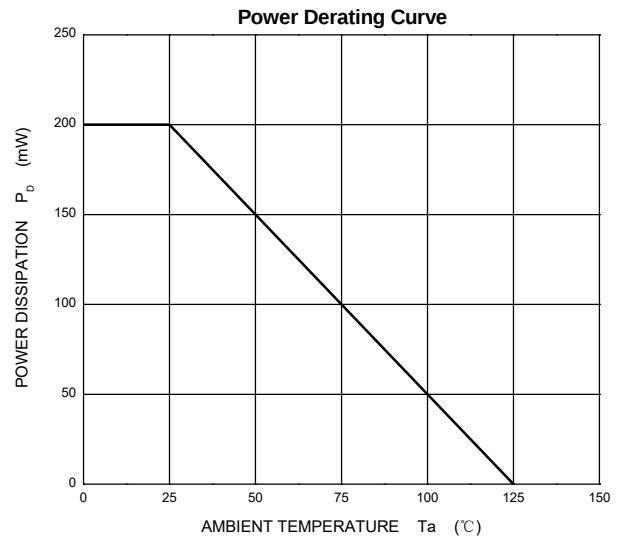
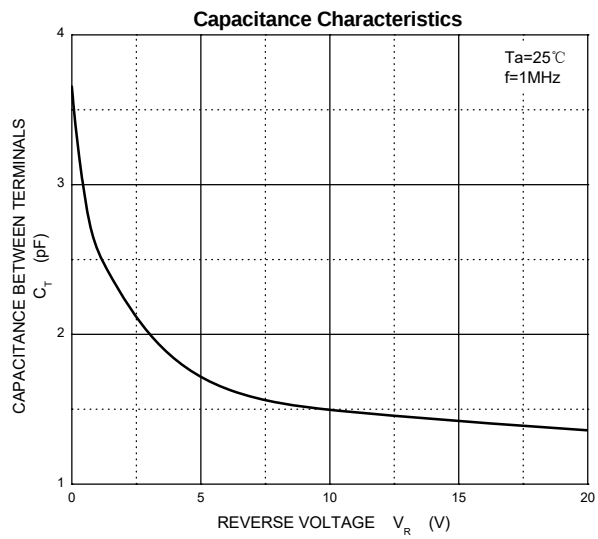
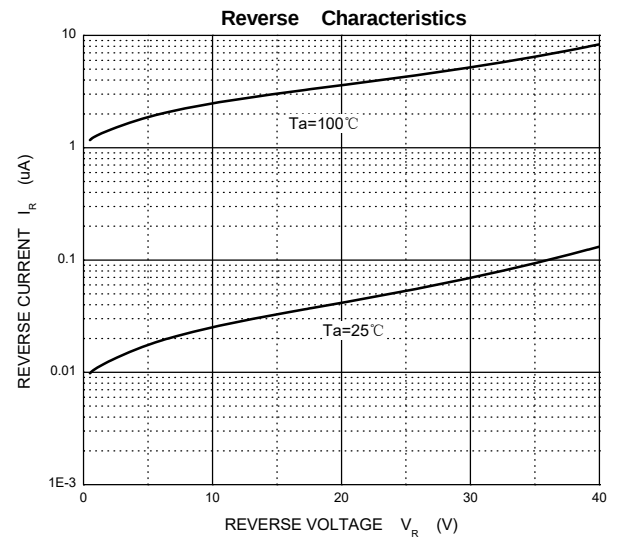
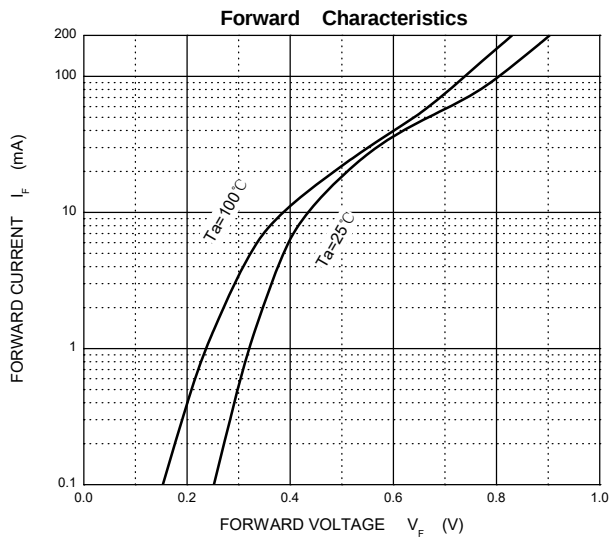
SOT-323

MARKING: 3D
Maximum Ratings @Ta=25 °C

Parameter	Symbol	Limit	Unit
Peak reverse voltage	V_{RM}	40	V
DC reverse voltage	V_R	40	V
Non-repetitive Peak Forward Surge current@t=8.3ms	I_{FSM}	200	mA
Average forward current	I_O	30	mA
Power dissipation	P_D	200	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	500	°C/W
Operating Junction Temperature Range	T_J	-40 ~ +125	°C
Storage Temperature Range	T_{stg}	-55 ~ +150	°C

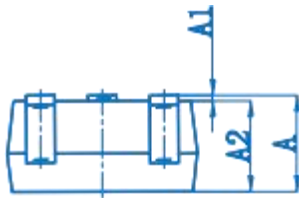
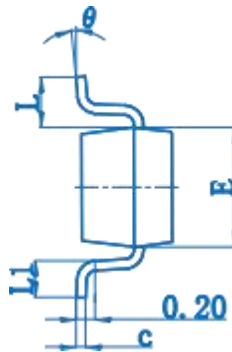
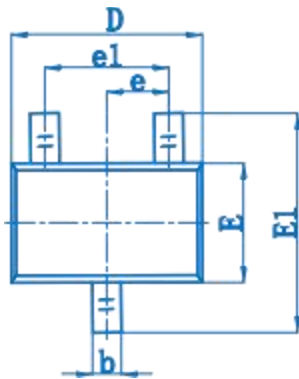
ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Reverse voltage leakage current	I_R	$V_R=10V$			1	μA
Forward voltage	V_F	$I_F=1mA$			0.37	V
Capacitance between terminals	C_T	$V_R=1V, f=1MHz$		2.0		pF

Typical Characteristics

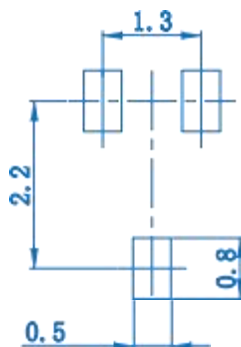


SOT-323 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

SOT-323 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.